

GP-2827

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE THE APPLICATION OF

Anslow et al.

SERIAL NO.: 09/451,127

FILED: November 30, 1999

FOR: HIGH DENSITY PRINTED WIRING BOARD
HAVING IN-VIA SURFACE MOUNTING PADS

) Examiner: Jeremy C. Norris

) Group Art Unit:
) 2827

) Docket No.: 476-1859

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to Commissioner for Patents, United States Patent and Trademark Office, Washington DC 20231, Box Responses, on November 5, 2002.
Name of person signing: Kathy Kurek
Signature Kathy Kurek

RESPONSE TO OFFICE ACTION OF SEPTEMBER 13, 2002

Honorable Commissioner for Patents
United States Patent and Trademark Office
Washington DC 20231

Dear Sir:

In response to the Examiner's further Office Action of September 13, 2002, it is requested that the application be amended as follows:

In the Claims:

4. (thrice amended) A printed circuit board comprising:-
- a) a plurality of spaced apart circuit layers;
 - b) a drill or laser formed blind hole/via extending between a surface circuit layer and at least one other circuit layer, said blind hole/via having an electrical connect layer which electrically connects said surface circuit layer to said at least one other circuit layer;

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- c) a reflow pad for mounting a component to the surface circuit layer, said reflow pad extending over a surface part of said electrical connect layer, and also extending over the blind hole/via, the surface part of the electrical connect layer extending a short distance over the surface of the surface circuit layer such that the reflow pad is located upon that part of the electrical connect layer that extends over the surface of the circuit layer; and
- d) an electro-conductive material filling the blind hole/via.

Cancel Claim 5 without prejudice.

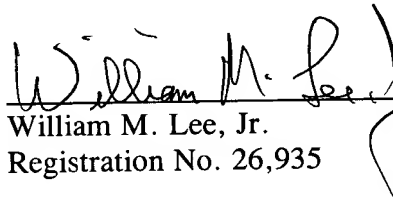
Remarks

In view of the Examiner's Office Action, where twice amended Claim 4 was rejected but Claim 5 was indicated to contain allowable subject matter, Claim 4 has been further amended to incorporate the subject matter of Claim 5, which has now also been cancelled.

It is therefore submitted that this application is in condition for allowance, and the Examiner's further and favorable reconsideration in that regard is urged.

Respectfully submitted,

Date: November 5, 2002


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